Designer's™ Data Sheet

Insulated Gate Bipolar Transistor

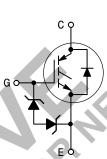
N-Channel Enhancement-Mode Silicon Gate

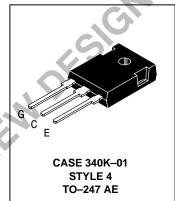
This Insulated Gate Bipolar Transistor (IGBT) is co–packaged with a soft recovery ultra–fast rectifier and uses an advanced termination scheme to provide an enhanced and reliable high voltage–blocking capability. Its new 600V IGBT technology is specifically suited for applications requiring both a high temperature short circuit capability and a low $V_{\text{CE}(on)}$. It also provides fast switching characteristics and results in efficient operation at high frequencies. Co–packaged IGBTs save space, reduce assembly time and cost. This new E–series introduces an energy efficient, ESD protected, and short circuit rugged device.

- Industry Standard TO-247 Package
- High Speed: E_{off} = 60 μJ/A typical at 125°C
- High Voltage Short Circuit Capability 10 μs minimum at 125°C, 400V
- Low On-Voltage 2.0V typical at 10A, 125°C
- · Soft Recovery Free Wheeling Diode is included in the Package
- Robust High Voltage Termination
- ESD Protection Gate-Emitter Zener Diodes

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IGBT IN TO-247
14 A @ 90°C
18 A @ 25°C
600 VOLTS
SHORT CIRCUIT RATED
ON-VOLTAGE





MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit	
Collector–Emitter Voltage	V _{CES}	600	Vdc	
Collector–Gate Voltage (R _{GE} = 1.0 MΩ)	V _{CGR}	600	Vdc	
Gate-Emitter Voltage — Continuous	V _{GE}	±20	Vdc	
Collector Current — Continuous @ T _C = 25°C — Continuous @ T _C = 90°C — Repetitive Pulsed Current (1)	I _{C25} I _{C90} I _{CM}	18 14 28	Adc Apk	
Total Power Dissipation @ T _C = 25°C Derate above 25°C	P _D	112 0.89	Watts W/°C	
Operating and Storage Junction Temperature Range	T _J , T _{stg}	-55 to 150	°C	
Short Circuit Withstand Time (V_{CC} = 400 Vdc, V_{GE} = 15 Vdc, T_J = 125°C, R_G = 20 Ω)	t _{sc}	10	μS	
Thermal Resistance — Junction to Case – IGBT — Junction to Case – Diode — Junction to Ambient	R _{θJC} R _{θJC} R _{θJA}	1.1 1.9 45	°C/W	
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 5 seconds	TL	260	°C	
Mounting Torque, 6–32 or M3 screw	10	10 lbf•in (1.13 N•m)		

⁽¹⁾ Pulse width is limited by maximum junction temperature. Repetitive rating.

Designer's Data for "Worst Case" Conditions — The Designer's Data Sheet permits the design of most circuits entirely from the information presented. SOA Limit curves — representing boundaries on device characteristics — are given to facilitate "worst case" design.

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$\textbf{ELECTRICAL CHARACTERISTICS} \ (T_J = 25^{\circ}C \ unless \ otherwise \ noted)$

Cha	racteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS						
Collector-to-Emitter Breakdown Volume (V _{GE} = 0 Vdc, I _C = 25 μAdc) Temperature Coefficient (Positive		V _{(BR)CES}	600	— 870	_	Vdc mV/°C
,	oltage (V _{GE} = 0 Vdc, I _{EC} = 100 mAdc)	V _{(BR)ECS}	15	_	_	Vdc
Zero Gate Voltage Collector Currer (V _{CE} = 600 Vdc, V _{GE} = 0 Vdc) (V _{CE} = 600 Vdc, V _{GE} = 0 Vdc, T _{GE}	nt	ICES		_ _ _	10 200	μAdc
Gate-Body Leakage Current (V _{GE}	= ± 20 Vdc, V _{CE} = 0 Vdc)	I _{GES}	_	_	50	μAdc
ON CHARACTERISTICS(1)		•			•	_
Collector-to-Emitter On-State Volto (V _{GE} = 15 Vdc, I _C = 5.0 Adc) (V _{GE} = 15 Vdc, I _C = 5.0 Adc, T _J = $(V_{GE} = 15 \text{ Vdc}, I_{C} = 10 \text{ Adc})$		V _{CE(on)}	_ _ _	1.6 1.5 2.0	1.9	Vdc
Gate Threshold Voltage (V _{CE} = V _{GE} , I _C = 1.0 mAdc) Threshold Temperature Coefficie	ent (Negative)	V _{GE(th)}	4.0 —	6.0 10	8.0 —	Vdc mV/°C
Forward Transconductance (V _{CE} =	10 Vdc, I _C = 10 Adc)	9 _{fe}		5.0	_	Mhos
DYNAMIC CHARACTERISTICS						
Input Capacitance		C _{ies}		1020	_	pF
Output Capacitance	$(V_{CE} = 25 \text{ Vdc}, V_{GE} = 0 \text{ Vdc}, f = 1.0 \text{ MHz})$	C _{oes}		104	_	
Transfer Capacitance		C _{res}	_	17	_]
SWITCHING CHARACTERISTICS(1						
Turn-On Delay Time		t _{d(on)}	_	38	_	ns
Rise Time		t _r	-	40	_	
Turn-Off Delay Time	$(V_{CC} = 360 \text{ Vdc}, I_C = 10 \text{ Adc},$	t _{d(off)}	-	120	_	
Fall Time	$V_{GE} = 15 \text{ Vdc}, L = 300 \mu\text{H}, R_{G} = 20 \Omega)$	t _f	-	204	_	
Turn-Off Switching Loss	Energy losses include "tail"	E _{off}	-	0.35	0.45	mJ
Turn-On Switching Loss		E _{on}	-	0.27	0.35	
Total Switching Loss		E _{ts}	_	0.62	0.80	
Turn-On Delay Time		t _{d(on)}	_	32	_	ns
Rise Time		t _r	_	30	_	
Turn-Off Delay Time	$(V_{CC} = 360 \text{ Vdc}, I_{C} = 10 \text{ Adc},$	t _{d(off)}	_	208	_	
Fall Time	$V_{GE} = 15 \text{ Vdc, L} = 300 \mu\text{H,}$ $R_{G} = 20 \Omega, T_{J} = 125^{\circ}\text{C}$	t _f	_	212	_	
Turn-Off Switching Loss	Energy losses include "tail"	E _{off}	_	0.63	_	mJ
Turn-On Switching Loss		E _{on}		0.40	_	
Total Switching Loss		E _{ts}		1.03	_	
Gate Charge		Q _T	_	57	_	nC
	$(V_{CC} = 360 \text{ Vdc}, I_{C} = 10 \text{ Adc}, V_{GE} = 15 \text{ Vdc})$	Q ₁	_	12	_	
,(0)	VGE = 13 VdC)	Q ₂	_	25	_	
DIODE CHARACTERISTICS						•
Diode Forward Voltage Drop (I _{EC} = 5.0 Adc) (I _{EC} = 5.0 Adc, T _J = 125°C)		V _{FEC}	— —	1.6 1.3	1.9	Vdc
(I _{EC} = 10 Adc)			1.7	2.0	2.3	<u> </u>

(1) Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.

(continued)

ELECTRICAL CHARACTERISTICS — **continued** (T_J = 25°C unless otherwise noted)

Cha	racteristic	Symbol	Min	Тур	Max	Unit
DIODE CHARACTERISTICS — cont	inued					
Reverse Recovery Time	(I _F = 10 Adc, V _R = 360 Vdc, dI _F /dt = 200 A/μs)	t _{rr}	_	75	_	ns
		ta	_	31	_	
		t _b	_	44	_	
Reverse Recovery Stored Charge		Q _{RR}	_	0.16	_	μС
Reverse Recovery Time	$(I_F = 10 \text{ Adc}, V_R = 360 \text{ Vdc},$ $dI_F/dt = 200 \text{ A/}\mu\text{s}, T_J = 125^{\circ}\text{C})$	t _{rr}	_	139	_	ns
		ta	_	45	_	
		t _b	_	94	_	
Reverse Recovery Stored Charge		Q _{RR}	_	0.40	_	μC
INTERNAL PACKAGE INDUCTANC	E					
Internal Emitter Inductance (Measured from the emitter lead (0.25" from package to emitter bond pad)	LE	_	7.5		nΗ

30

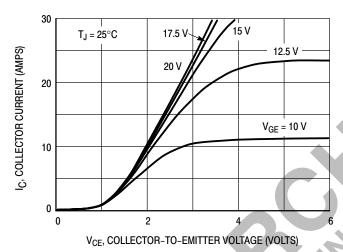


Figure 1. Output Characteristics

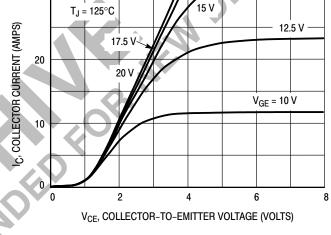


Figure 2. Output Characteristics

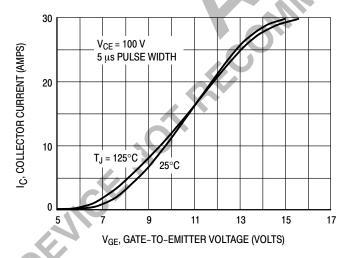


Figure 3. Transfer Characteristics

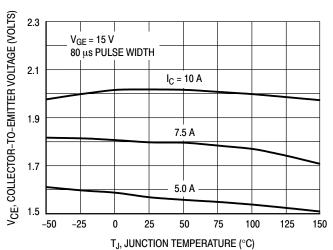


Figure 4. Collector–To–Emitter Saturation Voltage versus Junction Temperature

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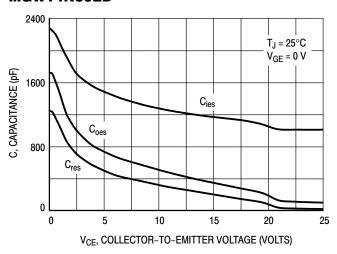


Figure 5. Capacitance Variation

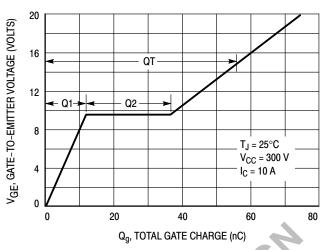


Figure 6. Gate-to-Emitter Voltage versus Total Charge

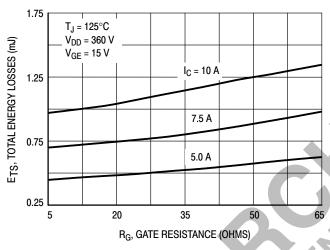


Figure 7. Total Energy Losses versus
Gate Resistance

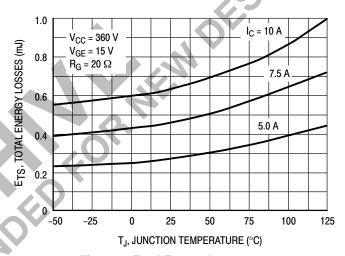


Figure 8. Total Energy Losses versus Junction Temperature

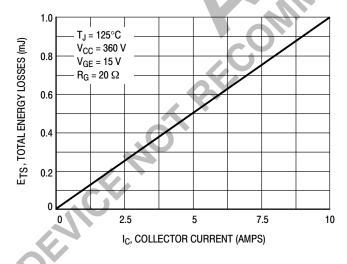


Figure 9. Total Energy Losses versus Collector Current

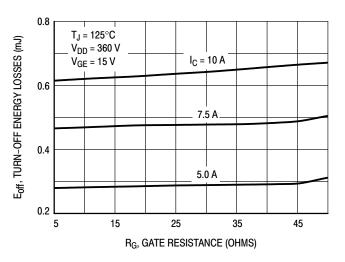


Figure 10. Turn-Off Energy Losses versus Gate Resistance

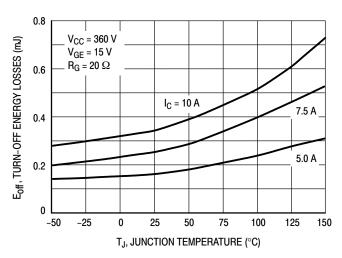


Figure 11. Turn-Off Energy Losses versus
Junction Temperature

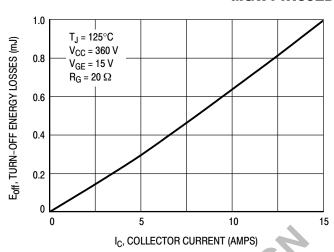


Figure 12. Turn-Off Energy Losses versus
Collector Current

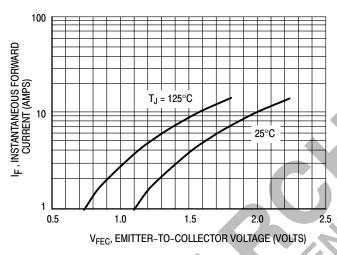


Figure 13. Forward Characteristics versus Current

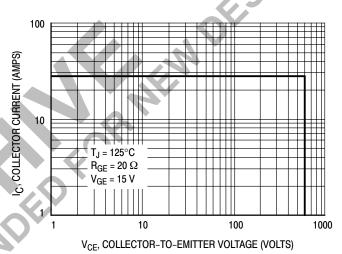
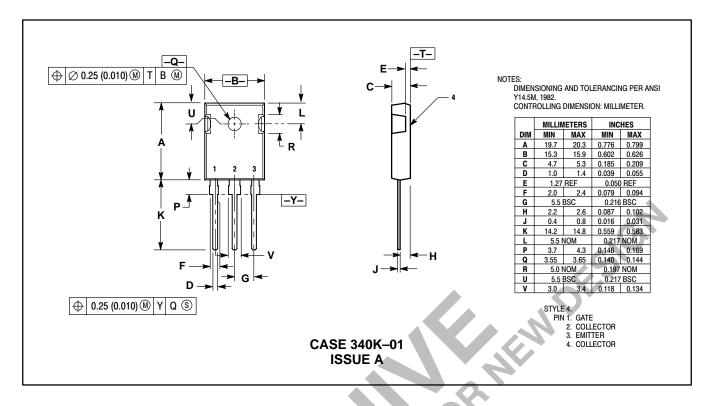


Figure 14. Reverse Biased Safe Operating Area

PACKAGE DIMENSIONS



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